

EAST Search History

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	20811	(chip or ic or "integrated circuit") same "through hole"	US-PGPUB; USPAT; EPO; JPO	OR	ON	2007/01/26 18:07
L2	9158	(chip or ic or "integrated circuit") same "through hole" same (sheet or layer or film)	US-PGPUB; USPAT; EPO; JPO	OR	ON	2007/01/26 18:08
L3	1619	(chip or ic or "integrated circuit") same "through hole" same (sheet or layer or film or substrate) same (smooth\$4 or bump\$5)	US-PGPUB; USPAT; EPO; JPO	OR	ON	2007/01/26 18:08
L4	157	(chip or ic or "integrated circuit") same "through hole" same (sheet or layer or film or substrate) same (smooth\$4 or bump\$5) same (before or prior)	US-PGPUB; USPAT; EPO; JPO	OR	ON	2007/01/26 18:08
L5	1	(chip or ic or "integrated circuit") same "through hole" same (sheet or layer or film or substrate) same (smooth\$4 or bump\$5) same (before or prior) same card	US-PGPUB; USPAT; EPO; JPO	OR	ON	2007/01/26 18:09
L6	41	(chip or ic or "integrated circuit") same "through hole" same (sheet or layer or film or substrate) same (smooth\$4 or bump\$5) same card	US-PGPUB; USPAT; EPO; JPO	OR	ON	2007/01/26 18:09
L7	877	card same (chip or ic or "integrated circuit") same "through hole"	US-PGPUB; USPAT; EPO; JPO	OR	ON	2007/01/26 18:19
L8	340	card same (chip or ic or "integrated circuit") same "through hole" same (layer or sheet or film)	US-PGPUB; USPAT; EPO; JPO	OR	ON	2007/01/26 18:22
L9	35	card same (chip or ic or "integrated circuit") same "through hole" same (layer or sheet or film) with plurality	US-PGPUB; USPAT; EPO; JPO	OR	ON	2007/01/26 18:23

EAST Search History

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	20811	(chip or ic or "integrated circuit") same "through hole"	US-PGPUB; USPAT; EPO; JPO	OR	ON	2007/01/26 18:07
L2	9158	(chip or ic or "integrated circuit") same "through hole" same (sheet or layer or film)	US-PGPUB; USPAT; EPO; JPO	OR	ON	2007/01/26 18:08
L3	1619	(chip or ic or "integrated circuit") same "through hole" same (sheet or layer or film or substrate) same (smooth\$4 or bump\$5)	US-PGPUB; USPAT; EPO; JPO	OR	ON	2007/01/26 18:08
L4	157	(chip or ic or "integrated circuit") same "through hole" same (sheet or layer or film or substrate) same (smooth\$4 or bump\$5) same (before or prior)	US-PGPUB; USPAT; EPO; JPO	OR	ON	2007/01/26 18:08
L5	1	(chip or ic or "integrated circuit") same "through hole" same (sheet or layer or film or substrate) same (smooth\$4 or bump\$5) same (before or prior) same card	US-PGPUB; USPAT; EPO; JPO	OR	ON	2007/01/26 18:09
L6	41	(chip or ic or "integrated circuit") same "through hole" same (sheet or layer or film or substrate) same (smooth\$4 or bump\$5) same card	US-PGPUB; USPAT; EPO; JPO	OR	ON	2007/01/26 18:09